HCB65S20D1Q

*e*SiC Silicon Carbide Schottky Diode

650V, 20A

Description

The 650V *e*SiC is an advanced Power Master Semiconductor's silicon carbide diode family. This technology combines the benefits of excellent low capacitive charge and robustness. Consequently, the *e*SiC family is suitable for application requiring high power efficiency.

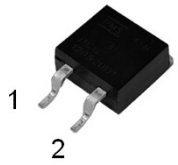
Applications

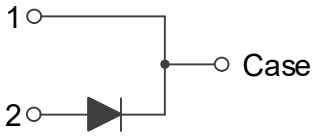
- Power Factor Correction
- Industrial Power Supplies
- Solar Inverter, UPS

Features

V_{RRM}	I_F	$T_{J,max}$	Q_C
650 V	20 A	175 ℃	61 nC

- No reverse recovery current
- Low capacitive charge
- 175°C Max junction temperature
- High surge current capability
- Switching behavior independent of temperature
- *P*b-Free, Halogen Free and RoHS compliant





Absolute Maximum Ratings (T_C = 25℃ unless otherwise noted)

Symbol	Parameter		Value	Unit
V_{RRM}	Repetitive Peak Reverse Voltage		650	V
I_F	Forward Current	T_C=127℃	20	A
$I_{F,SM}$	Non-Repetitive Forward Surge Current	T_C=25℃, t_p=10 ms	95	A
		T_C=150℃, t_p=10 ms	80.8	A
$I_{F,Max}$	Non-Repetitive Peak Forward Current	T_C=25℃, t_p=10 us	880	A
		T_C=150℃, t_p=10 us	748	A
I^2dt value	$\int I^2t$	T_C=25℃, t_p=10 ms	45.1	A^2S
		T_C=150℃, t_p=10 ms	32.6	A^2S
P_{tot}	Power Dissipation	T_C=25℃	125	W
T_J,T_{STG}	Operating Junction and Storage Temperature		-55 to +175	℃

Thermal Characteristics

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	1.2	℃/W

Package Marking and Ordering Information

Part Number	Top Marking	Package	Packing Method	Quantity
HCB65S20D1Q	HCB65S20D1Q	TO-263-2L	Tape & Reel	2500 units

Electrical Characteristics (T_C = 25℃ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Unit
V_F	Forward Voltage	I_F=20 A, T_C=25℃		1.40	1.7	V
		I_F=20 A, T_C=175℃		1.55	-	
I_R	Reverse Current	V_R=650 V, T_C=25℃		-	100	μA
		V_R=650 V, T_C=175℃		-	300	
Q_C	Total Capacitive Charge	V_R=400 V, T_C=25℃		61		nC
C	Total Capacitance	V_R=1 V, f=100 kHz		981		pF
		V_R=400 V, f=100 kHz		95		
E_C	Capacitance Stored Energy	V_R=400 V, T_C=25℃		8.9		μJ

Typical Performance Characteristics

Figure 1. Power Derating

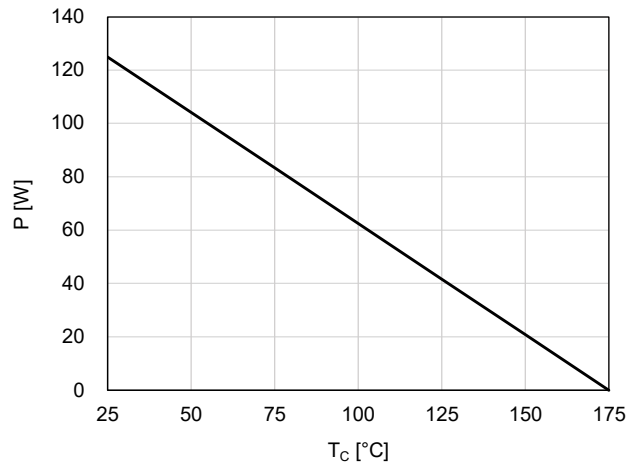


Figure 2. Current Derating

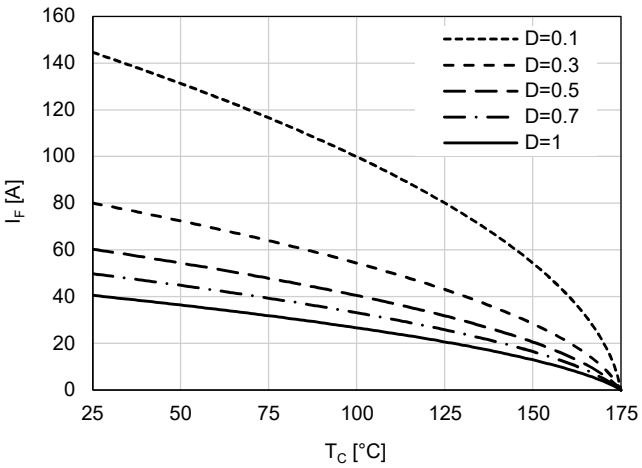


Figure 3. Forward Characteristics

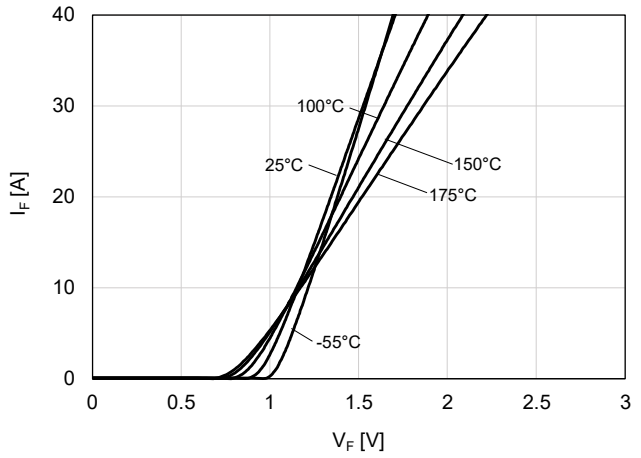


Figure 4. Reverse Characteristics

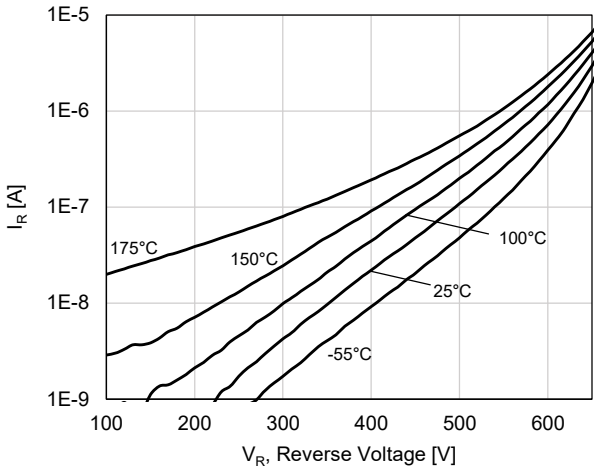


Figure 5. Capacitive Charge Characteristic

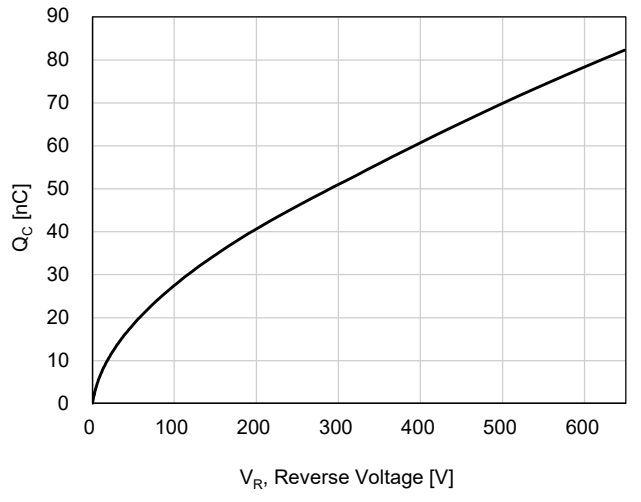
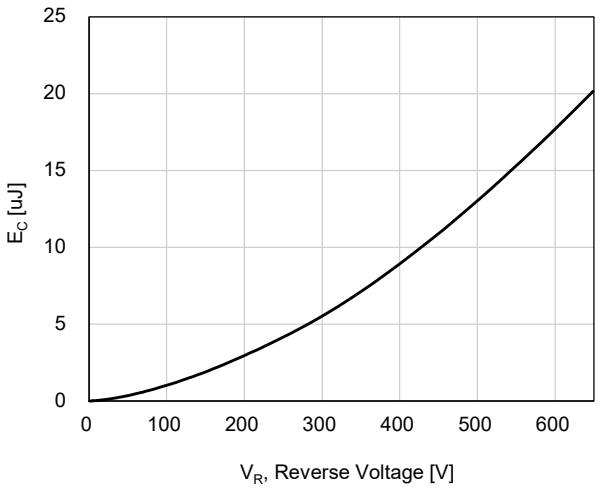


Figure 6. Capacitance Stored Energy



Typical Performance Characteristics

Figure 7. Capacitance Characteristic

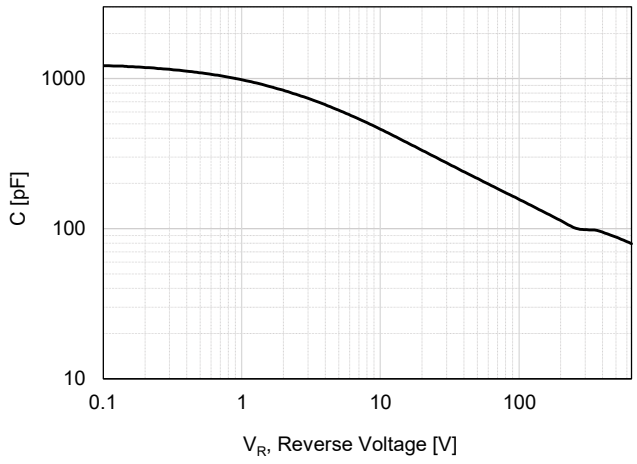
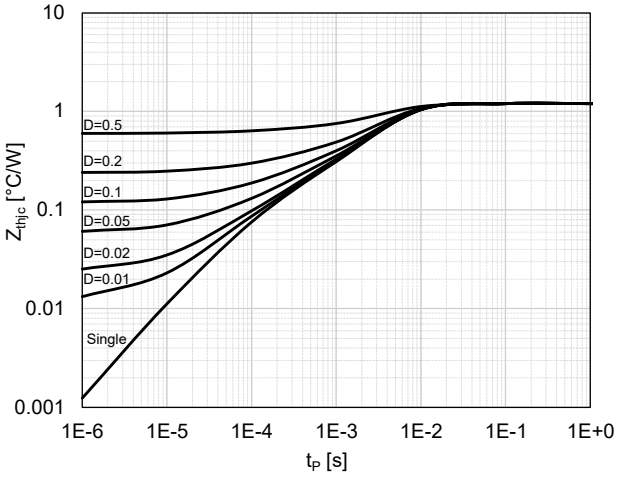
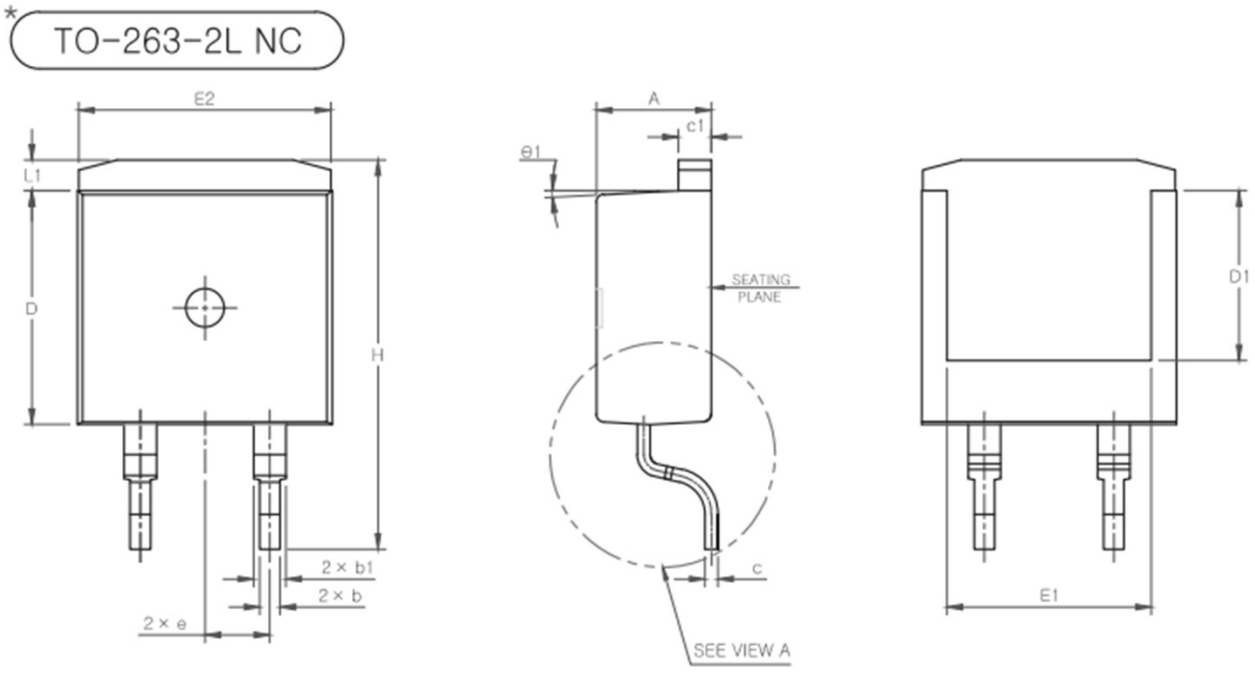


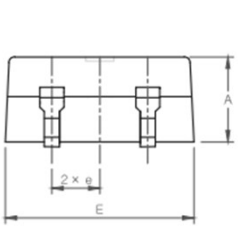
Figure 8. Transient Thermal Response Curve

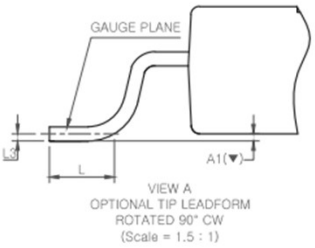


Package Outlines

TO-263-2L







VIEW A
OPTIONAL TIP LEADFORM
ROTATED 90° CW
(Scale = 1.5 : 1)

NOTE

1. THESE DIMENSIONS DO NOT INCLUDE PROTRUSIONS OF THE MOLD.
2. THE "( )" MARK IS THE REFERENCE
3. COPLANARITY : MAX 0.10mm

SYMBOL	MIN	NOM	MAX
A	4.30	4.50	4.70
A1(▼)	0.00	–	0.25
b	0.70	0.80	0.90
b1	1.17	1.27	1.37
c	0.45	0.50	0.60
c1	1.25	1.30	1.40
D	9.00	9.20	9.40
D1	6.50	6.70	6.90
E	9.80	10.00	10.20
E1	7.80	8.00	8.20
E2	9.70	9.90	10.10
e	2.54 BSC		
H	15.00	15.30	15.60
L	2.00	2.30	2.60
L1	1.00	1.20	1.40
L3	0.254 BSC		
θ1	(3°)		

* Dimensions in millimeters